PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Mou-Shiung Lin	05/16/2007
Huei-Mei Yen	06/28/2007
Chiu-Ming Chou	06/28/2007
Hsin-Jung Lo	06/05/2007
Ke-Hung Chen	05/16/2007

RECEIVING PARTY DATA

Name:	MEGICA CORPORATION	
Street Address:	Room 301/302, No. 47, Park 2nd Rd.	
Internal Address:	Science-Based Industrial Park	
City:	Hsinchu	
State/Country:	TAIWAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13094780

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	Dennis A. Duchene

Total Attachments: 2

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> **PATENT REEL: 026664 FRAME: 0350**





ASSIGNMENT

WHEREAS.

1. Mou-Shiung Lin

2. Huei-Mei Yen

3. Chiu-Ming Chou

4. Hsin-Jung Lo

5. Ke-Hung Chen

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: SEMICONDUCTOR CHIP

[] Filed: 12/5/2006

Serial No. 11/567,182

[x] Executed concurrently with the execution of this instrument

WHEREAS, Megica Corporation

of Room 301/302, No.47, Park 2nd Rd., Science-Based Industrial Park Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

PATENT REEL: 026664 FRAME: 0351

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated. Sole or First Joint Inventor: Mou-Shiung Lin Second Joint Inventor (if any): Huei-Mei Yen Third Joint Inventor (if any): Chiu-Ming Chou Fourth Joint Inventor (if any): Hsin-Jung Lo Date: 5/16 (2007 Fifth Joint Inventor (if any): Ke-Hung Chen

> PATENT REEL: 026664 FRAME: 0352

RECORDED: 07/28/2011